

MC10E111, MC100E111

5 V ECL 1:9 Differential Clock Driver

Description

The MC10E/100E111 is a low skew 1-to-9 differential driver, designed with clock distribution in mind. It accepts one signal input, which can be either differential or else single-ended if the V_{BB} output is used. The signal is fanned out to 9 identical differential outputs. An enable input is also provided. A HIGH disables the device by forcing all Q outputs LOW and all \bar{Q} outputs HIGH.

The device is specifically designed, modeled and produced with low skew as the key goal. Optimal design and layout serve to minimize gate to gate skew within-device, and empirical modeling is used to determine process control limits that ensure consistent t_{pd} distributions from lot to lot. The net result is a dependable, guaranteed low skew device.

The lowest TPD delay time results from terminating only one output pair, and the greatest TPD delay time results from terminating all the output pairs. This shift is about 10–20 pS in TPD. The skew between any two output pairs within a device is typically about 25 nS. If other output pairs are not terminated, the lowest TPD delay time results from both output pairs and the skew is typically 25 nS. When all outputs are terminated, the greatest TPD (delay time) occurs and all outputs display about the same 10–20 pS increase in TPD, so the relative skew between any two output pairs remains about 25 nS.

The V_{BB} pin, an internally generated voltage supply, is available to this device only. For single-ended input conditions, the unused differential input is connected to V_{BB} as a switching reference voltage. V_{BB} may also rebias AC coupled inputs. When used, decouple V_{BB} and V_{CC} via a 0.01 μ F capacitor and limit current sourcing or sinking to 0.5 mA. When not used, V_{BB} should be left open.

The 100 Series contains temperature compensation.

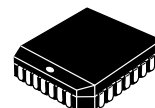
Features

- Guaranteed Skew Spec
- Differential Design
- V_{BB} Output
- PECL Mode Operating Range: $V_{CC} = 4.2$ V to 5.7 V with $V_{EE} = 0$ V
- NECL Mode Operating Range: $V_{CC} = 0$ V with $V_{EE} = -4.2$ V to -5.7 V
- Internal Input 50 K Ω Pulldown Resistors
- ESD Protection: > 3 kV Human Body Model
- Meets or Exceeds JEDEC Standard EIA/JESD78 IC Latchup Test
- Moisture Sensitivity: Level 3 (Pb-Free)
(For Additional Information, see Application Note [AND8003/D](#))
- Flammability Rating: UL 94 V-0 @ 0.125 in, Oxygen Index: 28 to 34
- Transistor Count = 178 Devices
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant



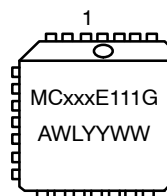
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PLCC-28
FN SUFFIX
CASE 776-02

MARKING DIAGRAM*



xxx = 10 or 100
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
G = Pb-Free Package

*For additional marking information, refer to Application Note [AND8002/D](#).

ORDERING INFORMATION

Device	Package	Shipping†
MC10E111FNG	PLCC-28 (Pb-Free)	37 Units/Tube
MC10E111FNR2G	PLCC-28 (Pb-Free)	500 Tape & Reel
MC100E111FNG	PLCC-28 (Pb-Free)	37 Units/Tube
MC100E111FNR2G	PLCC-28 (Pb-Free)	500 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

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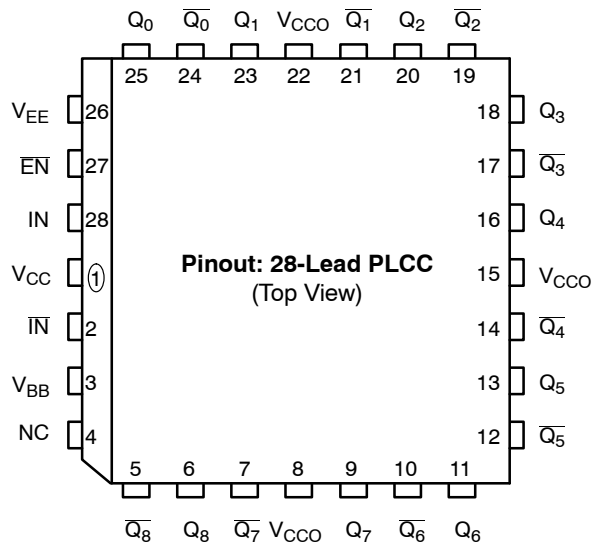


Table 1. PIN DESCRIPTION

PIN	FUNCTION
IN, \overline{IN}	ECL Differential Input Pair
EN	ECL Enable
$Q_0, \overline{Q_0}-Q_8, \overline{Q_8}$	ECL Differential Outputs
V_{BB}	Reference Voltage Output
V_{CC}, V_{CCO}	Positive Supply
V_{EE}	Negative Supply
NC	No Connect

* All V_{CC} and V_{CCO} pins are tied together on the die.

Warning: All V_{CC} , V_{CCO} , and V_{EE} pins must be externally connected to Power Supply to guarantee proper operation.

Figure 1. 28-Lead Pinout

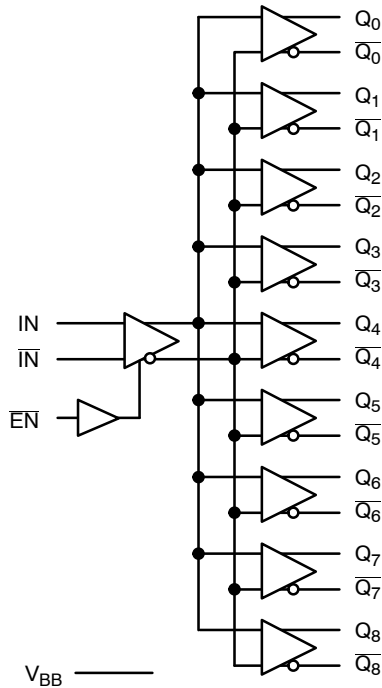


Figure 2. Logic Symbol

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Table 2. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V _{CC}	PECL Mode Power Supply	V _{EE} = 0 V		8	V
V _I	PECL Mode Input Voltage NECL Mode Input Voltage	V _{EE} = 0 V V _{CC} = 0 V	V _I ≤ V _{CC} V _I ≥ V _{EE}	6 -6	V
I _{out}	Output Current	Continuous Surge		50 100	mA
I _{BB}	V _{BB} Sink/Source			±0.5	mA
T _A	Operating Temperature Range			-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
θ _{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	PLCC-28 PLCC-28	63.5 43.5	°C/W
θ _{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	PLCC-28	22 to 26	°C/W
T _{sol}	Wave Solder (Pb-Free)			265	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 3. 10E SERIES PECL DC CHARACTERISTICS (V_{CCx} = 5.0 V; V_{EE} = 0.0 V (Note 1))

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I _{EE}	Power Supply Current		41	60		42	60		43	60	mA
V _{OH}	Output HIGH Voltage (Note 2)	3920	4030	4110	4020	4105	4190	4090	4185	4280	mV
V _{OL}	Output LOW Voltage (Note 2)	3050	3230	3350	3050	3210	3370	3050	3227	3405	mV
V _{IH}	Input HIGH Voltage (Single-Ended)	3870	4030	4190	3870	4030	4190	3940	4110	4280	mV
V _{IL}	Input LOW Voltage (Single-Ended)	3050	3285	3520	3050	3285	3520	3050	3302	3555	mV
V _{BB}	Output Voltage Reference	3.6		3.73	3.65		3.75	3.69		3.90	V
V _{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 3)	3.4		4.6	3.4		4.6	3.4		4.6	V
I _{IH}	Input HIGH Current			150			150			150	μA
I _{IL}	Input LOW Current	0.5			0.5	0.25		0.3	0.2		μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

1. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary -0.46 V / +0.06 V.
2. Outputs are terminated through a 50 Ω resistor to V_{CC} - 2.0 V.
3. V_{IHCMR} min and max vary 1:1 with V_{CC}.

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Table 4. 10E SERIES NECL DC CHARACTERISTICS ($V_{CCx} = 0.0\text{ V}$; $V_{EE} = -5.0\text{ V}$ (Note 1))

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current		41	60		42	60		43	60	mA
V_{OH}	Output HIGH Voltage (Note 2)	-1080	-970	-890	-980	-895	-810	-910	-815	-720	mV
V_{OL}	Output LOW Voltage (Note 2)	-1950	-1770	-1650	-1950	-1790	-1630	-1950	-1773	-1595	mV
V_{IH}	Input HIGH Voltage (Single-Ended)	-1130	-970	-810	-1130	-970	-810	-1060	-890	-720	mV
V_{IL}	Input LOW Voltage (Single-Ended)	-1950	-1715	-1480	-1950	-1715	-1480	-1950	-1698	-1445	mV
V_{BB}	Output Voltage Reference	-1.40		-1.27	-1.35		-1.25	-1.31		-1.19	V
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 3)	-1.6		-0.4	-1.6		-0.4		1.6	-0.4	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5			0.5	0.065		0.3	0.2		μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

1. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary $-0.46\text{ V} / +0.06\text{ V}$.
2. Outputs are terminated through a $50\ \Omega$ resistor to $V_{CC} - 2.0\text{ V}$.
3. V_{IHCMR} min and max vary 1:1 with V_{CC} .

Table 5. 100E SERIES PECL DC CHARACTERISTICS ($V_{CCx} = 5.0\text{ V}$; $V_{EE} = 0.0\text{ V}$ (Note 1))

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current		40	60		45	60		50	69	mA
V_{OH}	Output HIGH Voltage (Note 2)	3975	4020	4120	3975	4020	4120	3975	4020	4120	mV
V_{OL}	Output LOW Voltage (Note 2)	3190	3300	3380	3190	3300	3380	3190	3300	3380	mV
V_{IH}	Input HIGH Voltage (Single-Ended)	3835	3975	4120	3835	3975	4120	3835	3975	4120	mV
V_{IL}	Input LOW Voltage (Single-Ended)	3190	3355	3525	3190	3355	3525	3190	3355	3525	mV
V_{BB}	Output Voltage Reference	3.64		3.75	3.62		3.74	3.62		3.74	V
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 3)	3.4		4.6	3.4		4.6	3.4		4.6	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5			0.5	0.25		0.5	0.2		μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

1. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary $-0.46\text{ V} / +0.8\text{ V}$.
2. Outputs are terminated through a $50\ \Omega$ resistor to $V_{CC} - 2.0\text{ V}$.
3. V_{IHCMR} min and max vary 1:1 with V_{CC} .

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Table 6. 100E SERIES NECL DC CHARACTERISTICS ($V_{CCx} = 0.0\text{ V}$; $V_{EE} = -5.0\text{ V}$ (Note 1))

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current		40	60		45	60		50	69	mA
V_{OH}	Output HIGH Voltage (Note 2)	-1025	-980	-880	-1025	-980	-880	-1025	-980	-880	mV
V_{OL}	Output LOW Voltage (Note 2)	-1810	-1700	-1620	-1810	-1700	-1620	-1810	-1700	-1620	mV
V_{IH}	Input HIGH Voltage (Single-Ended)	-1165	-1025	-880	-1165	-1025	-880	-1165	-1025	-880	mV
V_{IL}	Input LOW Voltage (Single-Ended)	-1810	-1645	-1475	-1810	-1645	-1475	-1810	-1645	-1475	mV
V_{BB}	Output Voltage Reference	-1.38		-1.25	-1.38		-1.26	-1.38		-1.26	V
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 3)	-1.6		-0.4	-1.6		-0.4	-1.6		-0.4	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5			0.5	0.25		0.5	0.2		μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

1. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary $-0.46\text{ V} / +0.8\text{ V}$.
2. Outputs are terminated through a $50\ \Omega$ resistor to $V_{CC} - 2.0\text{ V}$
3. V_{IHCMR} min and max vary 1:1 with V_{CC} .

Table 7. AC CHARACTERISTICS ($V_{CCx} = 5.0\text{ V}$; $V_{EE} = 0.0\text{ V}$ or $V_{CCx} = 0.0\text{ V}$; $V_{EE} = -5.0\text{ V}$ (Note 1))

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
f_{MAX}	Maximum Toggle Frequency		800			800			800		MHz
t_{PLH} t_{PHL}	Propagation Delay to Output IN (Diff) (Note 2) IN (SE) (Note 3) Enable (Note 4) Disable (Note 4)	430 380 400 400		630 680 900 900	430 380 450 450		630 680 850 850	430 380 450 450		630 680 850 850	ps
t_s	Setup Time (Note 5) EN to IN	250	0		200	0		200	0		ps
t_H	Hold Time (Note 6) IN to EN	50	-200		0	-200		0	-200		ps
t_R	Release Time (Note 7) EN to IN	350	100		300	100		300	100		ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

1. 10 Series: V_{EE} can vary $-0.46\text{ V} / +0.06\text{ V}$.
100 Series: V_{EE} can vary $-0.46 / +0.8\text{ V}$.
2. The differential propagation delay is defined as the delay from the crossing points of the differential input signals to the crossing point of the differential output signals.
3. The single-ended propagation delay is defined as the delay from the 50% point of the input signal to the 50% point of the output signal.
4. Enable is defined as the propagation delay from the 50% point of a **negative** transition on EN to the 50% point of a **positive** transition on Q (or a negative transition on \bar{Q}). Disable is defined as the propagation delay from the 50% point of a **positive** transition on EN to the 50% point of a **negative** transition on Q (or a positive transition on \bar{Q}).
5. The setup time is the minimum time that EN must be asserted prior to the next transition of IN/ \bar{IN} to prevent an output response greater than $\pm 75\text{ mV}$ to that IN/ \bar{IN} transition (Figure 3).
6. The hold time is the minimum time that EN must remain asserted after a negative going IN or a positive going \bar{IN} to prevent an output response greater than $\pm 75\text{ mV}$ to that IN/ \bar{IN} transition (Figure 4).
7. The release time is the minimum time that EN must be deasserted prior to the next IN/ \bar{IN} transition to ensure an output response that meets the specified IN to Q propagation delay and output transition times (Figure 5).
8. The within-device skew is defined as the worst case difference between any two similar delay paths within a single device.

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Table 7. AC CHARACTERISTICS ($V_{CCx} = 5.0\text{ V}$; $V_{EE} = 0.0\text{ V}$ or $V_{CCx} = 0.0\text{ V}$; $V_{EE} = -5.0\text{ V}$ (Note 1))

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
t_{skew}	Within-Device Skew (Note 8)		25	75		25	50		25	50	ps
t_{JITTER}	Random Clock Jitter (RMS)		< 1	< 2		< 1	< 2		< 1	< 2	ps
V_{PP}	Minimum Input Swing	50			50			50			mV
t_r, t_f	Rise/Fall Time	250	450	650	275	375	600	275	375	600	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 10 Series: V_{EE} can vary $-0.46\text{ V} / +0.06\text{ V}$.
100 Series: V_{EE} can vary $-0.46 / +0.8\text{ V}$.
- The differential propagation delay is defined as the delay from the crossing points of the differential input signals to the crossing point of the differential output signals.
- The single-ended propagation delay is defined as the delay from the 50% point of the input signal to the 50% point of the output signal.
- Enable is defined as the propagation delay from the 50% point of a **negative** transition on \overline{EN} to the 50% point of a **positive** transition on Q (or a negative transition on \overline{Q}). Disable is defined as the propagation delay from the 50% point of a **positive** transition on \overline{EN} to the 50% point of a **negative** transition on Q (or a positive transition on \overline{Q}).
- The setup time is the minimum time that \overline{EN} must be asserted prior to the next transition of IN/\overline{IN} to prevent an output response greater than $\pm 75\text{ mV}$ to that IN/\overline{IN} transition (Figure 3).
- The hold time is the minimum time that \overline{EN} must remain asserted after a negative going IN or a positive going \overline{IN} to prevent an output response greater than $\pm 75\text{ mV}$ to that IN/\overline{IN} transition (Figure 4).
- The release time is the minimum time that \overline{EN} must be deasserted prior to the next IN/\overline{IN} transition to ensure an output response that meets the specified IN to Q propagation delay and output transition times (Figure 5).
- The within-device skew is defined as the worst case difference between any two similar delay paths within a single device.

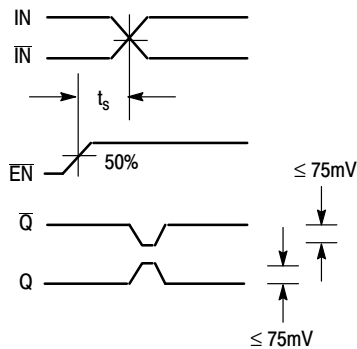


Figure 3. Setup Time

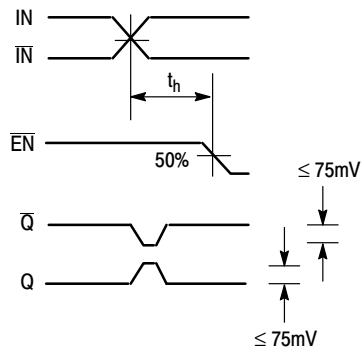


Figure 4. Hold Time

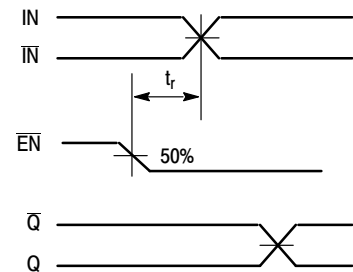


Figure 5. Release Time

MC10E111, MC100E111

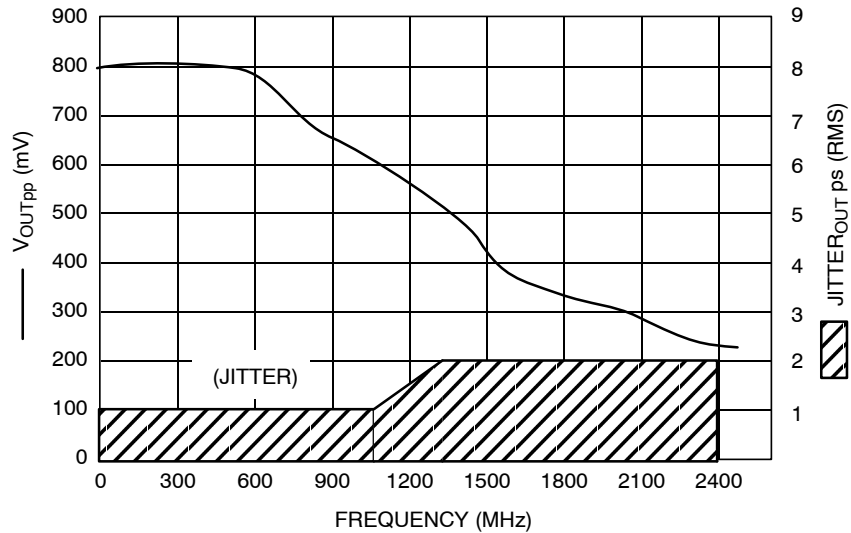


Figure 6. F_{max}/Jitter

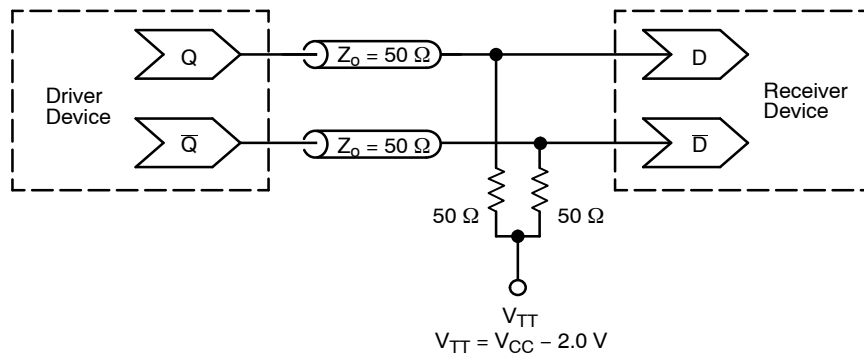


Figure 7. Typical Termination for Output Driver and Device Evaluation
(See Application Note [AND8020/D](#) – Termination of ECL Logic Devices)

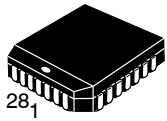
Resource Reference of Application Notes

- AN1405/D** – ECL Clock Distribution Techniques
- AN1406/D** – Designing with PECL (ECL at +5.0 V)
- AN1503/D** – ECLinPS™ I/O SPICE Modeling Kit
- AN1504/D** – Metastability and the ECLinPS Family
- AN1568/D** – Interfacing Between LVDS and ECL
- AN1672/D** – The ECL Translator Guide
- AND8001/D** – Odd Number Counters Design
- AND8002/D** – Marking and Date Codes
- AND8020/D** – Termination of ECL Logic Devices
- AND8066/D** – Interfacing with ECLinPS
- AND8090/D** – AC Characteristics of ECL Devices

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

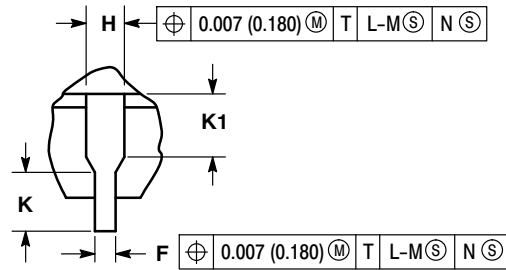
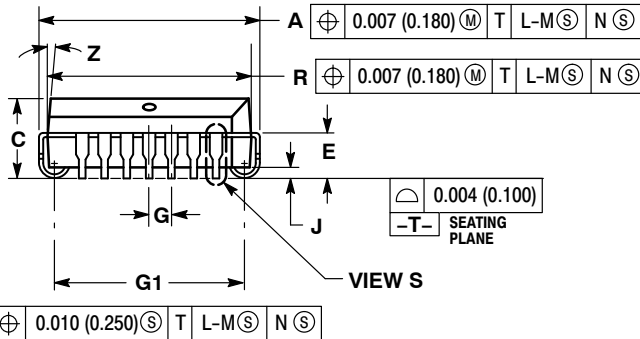
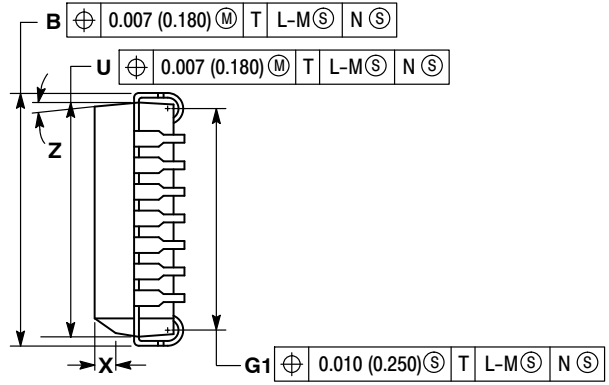
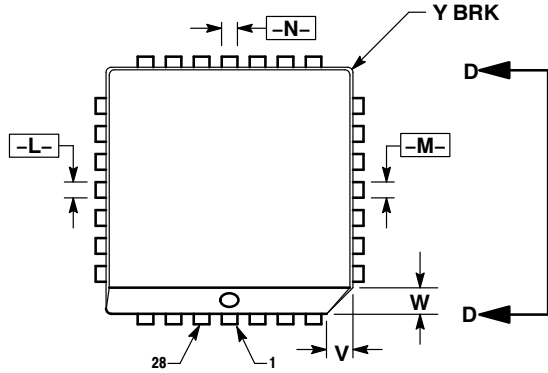
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SCALE 1:1

28 LEAD PLLC
CASE 776-02
ISSUE F

DATE 29 JUL 2008

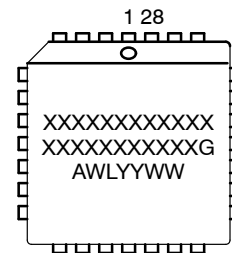


NOTES:

- DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
- DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.
- DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
- THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.485	0.495	12.32	12.57
B	0.485	0.495	12.32	12.57
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.021	0.33	0.53
G	0.050 BSC		1.27 BSC	
H	0.026	0.032	0.66	0.81
J	0.020	---	0.51	---
K	0.025	---	0.64	---
R	0.450	0.456	11.43	11.58
U	0.450	0.456	11.43	11.58
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	---	0.020	---	0.50
Z	2° 10°		2° 10°	
G1	0.410	0.430	10.42	10.92
K1	0.040	---	1.02	---

GENERIC MARKING DIAGRAM*



- XXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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